2SD1275, 2SD1275A

Silicon NPN triple diffusion planar type Darlington

For power amplification

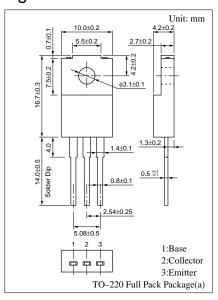
Complementary to 2SB0949 (2SB949) and 2SB0949A (2SB949A)

Features

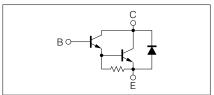
- High foward current transfer ratio h_{FE}
- High-speed switching
- Full-pack package which can be installed to the heat sink with one screw

Absolute Maximum Ratings (T_C=25°C)

Parameter		Symbol	Ratings	Unit	
Collector to	2SD1275	V	60	V	
base voltage	2SD1275A	V_{CBO}	80		
Collector to	2SD1275	37	60		
emitter voltage	2SD1275A	V_{CEO}	80	V	
Emitter to base voltage		$V_{\rm EBO}$	5	V	
Peak collector current		I_{CP}	4	A	
Collector current		I_C	2	A	
Collector power	T _C =25°C	D	35	W	
dissipation	Ta=25°C	P_{C}	2		
Junction temperature		T _j	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



Internal Connection



Electrical Characteristics (T_C=25°C)

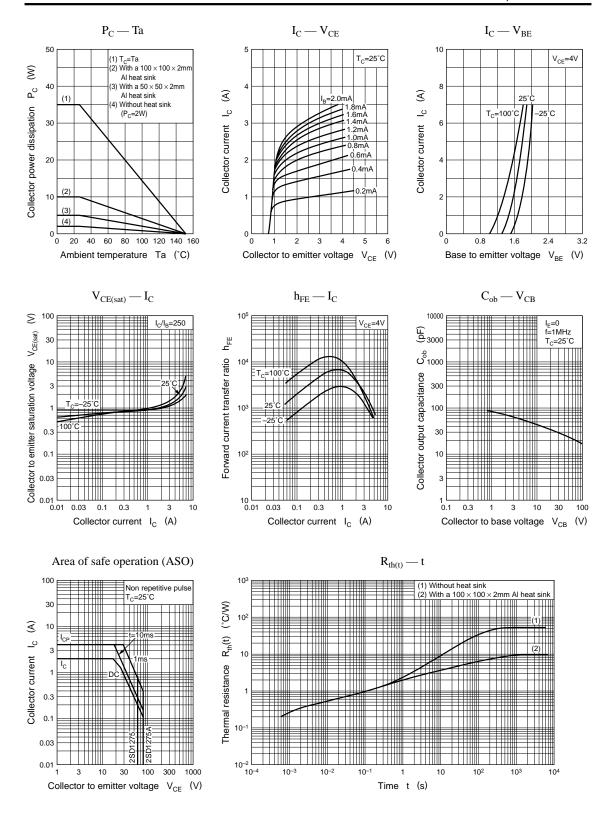
Paramete	er	Symbol	Conditions	min	typ	max	Unit
Collector cutoff	2SD1275	I_{CBO}	$V_{CB} = 60V, I_E = 0$			1	mA
current	2SD1275A		$V_{CB} = 80V, I_{E} = 0$			1	
Collector cutoff	2SD1275	I _{CEO}	$V_{CE} = 30V, I_{B} = 0$			2	mA
current	2SD1275A		$V_{CE} = 40V, I_{B} = 0$			2	
Emitter cutoff current		I_{EBO}	$V_{\rm EB} = 5V, I_{\rm C} = 0$			2	mA
Collector to emitter	2SD1275	V _{CEO}		60			V
voltage	2SD1275A		$I_{C} = 30\text{mA}, I_{B} = 0$	80			
Forward current transfer ratio		h _{FE1}	$V_{CE} = 4V$, $I_C = 1A$	1000			
		h _{FE2} *	$V_{CE} = 4V, I_C = 2A$	2000		10000	
Base to emitter voltage		V _{BE}	$V_{CE} = 4V$, $I_C = 2A$			2.8	V
Collector to emitter saturation voltage		V _{CE(sat)}	$I_C = 2A, I_B = 8mA$			2.5	V
Transition frequency		f_T	$V_{CE} = 10V, I_C = 0.5A, f = 1MHz$		20		MHz
Turn-on time		t _{on}	$I_C = 2A$, $I_{B1} = 8mA$, $I_{B2} = -8mA$,		0.5		μs
Storage time		t _{stg}			4		μs
Fall time		t _f	$V_{CC} = 50V$		1		μs

*h_{FE2} Rank classification

Rank	Q	P
h _{FE2}	2000 to 5000	4000 to 10000

Note) The part numbers in the parenthesis show conventional part number.

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